

ABSTRACT

A thermosetting polyamide foam prepared by reacting a polyisocyanate compound with a polyester polycarboxylic acid using a compound having a P=N bond as a catalyst under conditions of an NCO index of not less than 1.6. The polyamide foam is excellent in heat resistance (thermal decomposition resistance) and moldability, and is applicable for heat-resistant vibration dampers, heat-resistant sound-absorbing materials and heat-resistant cushioning materials.